

DACxx68EVM

The DACxx68 Evaluation Module is an evaluation board containing all the necessary components to evaluate the eight-channel DAC7568, DAC8168, or DAC8568 series of high-performance digital-to-analog converters from Texas Instruments. The EVM is designed so that a single printed-circuit board (PCB) supports the entire family of high-speed, 12- to 16-bit serial DACs. The EVM is provided with Grade C devices which reset to zero and have a full-scale output range of 0 V to 5 V.

The modular EVM form factor allows for direct evaluation of the DAC's performance and operating characteristics. This EVM is compatible with the 5-6K Interface Board ([SLAU104](#)) from Texas Instruments as well as the HPA-MCU Interface Board ([SLAU106](#)).

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1 EVM Overview

- Full-featured Evaluation Board for the 12-/14-/16-bit, eight-channel DAC7568, DAC8168, or DAC8568 digital-to-analog converters
- Onboard reference and buffer circuits
- High-speed serial interface
- Modular design for use with a variety of DSP and DACxx68 DAC Controller Interface Boards

2 Analog Interface

For maximum flexibility, the DACxx68EVM is designed for easy interfacing to multiple analog sources. Samtec part numbers SSW-110-22-F-D-VS-K and TSM-110-01-T-DV-P provide a convenient 10-pin, dual-row header/socket combination at J2. This header/socket provides access to the analog input pins of the ADC. Consult Samtec at www.samtec.com or call 1-800-SAMTEC-9 for a variety of mating connector options.

| Pin Number | Signal | Description |
|------------------|-----------|--------------------------------------------------------------|
| J2.2 | DAC OUT_G | Voltage output for DAC channel G |
| J2.4 | DAC OUT_E | Voltage output for DAC channel E |
| J2.6 | DAC OUT_C | Voltage output for DAC channel C |
| J2.8 | DAC OUT_A | Voltage output for DAC channel A |
| J2.10 | DAC OUT_B | Voltage output for DAC channel B |
| J2.12 | DAC OUT_D | Voltage output for DAC channel D |
| J2.14 | DAC OUT_F | Voltage output for DAC channel F |
| J2.16 | DAC OUT_H | Voltage output for DAC channel H |
| J2.18 | REF(-) | Unused |
| J2.20 | REF(+) | External reference source input (2.5 V NOM, 2.525 V maximum) |
| J2.15 | VCOM | Common-mode voltage output option |
| J2.1–J2.19 (odd) | AGND | Analog ground connections (except J2.15) |

3 Digital Interface

The DACxx68EVM is designed for easy interfacing to multiple control platforms. Samtec part numbers SSW-110-22-F-D-VS-K and TSM-110-01-T-DV-P provide a convenient 10-pin, dual-row header/socket combination at J2. This header/socket provides access to the digital control and serial data pins of the DACxx68 DAC EVM. Consult Samtec at www.samtec.com or 1-800-SAMTEC-9 for a variety of mating connector options.

Table 1. Digital Control

| Pin Number | Signal | Description |
|------------|---------|----------------------------------------------------------------------------------------------|
| J2.1 | CNTL | Active-low input to SYNC enables data transfer – jumper configurable (see schematic) via JP5 |
| J2.3 | SCLK | Serial clock |
| J2.5 | SCLK(R) | Serial clock return (for DSP host systems) |
| J2.7 | FSX | Frame synchronization for DSP host systems – default SYNC input through JP5 (see schematic) |
| J2.9 | FS(R) | Frame synchronization return (for DSP host systems) |
| J2.11 | DX | Serial data input |
| J2.13 | DR | Unused – Serial data return (for DSP host systems) |
| J2.15 | INT | External source for LOAD DAC (LDAC) strobe via JP6 |
| J2.17 | TOUT | Default source for LOAD DAC (LDAC) strobe via JP6 |
| J2.19 | GPIO5 | Optional source for active low CLEAR (CLR) input |

Table 1. Digital Control (continued)

| Pin Number | Signal | Description |
|------------|--------|---------------------|
| J2.4 | GND | System (EVM) ground |
| J2.10 | | |
| J2.18 | | |

4 Power Supplies

The DACxx68EVM board is built with grade C devices and requires a single +5 V DC for proper operation. This 5-V supply powers the onboard voltage reference (U2) and the common-mode voltage output buffer (U3). When used in combination with one of the DAP Interface boards, J3 provides connection to the common power bus described in document [SLAA185](#). [Table 2](#) shows the pinout of J3.

Table 2. J3 Power Input

| Signal | Pin Number | | Signal |
|--------|------------|----|--------|
| Unused | 1 | 2 | Unused |
| +5VA | 3 | 4 | Unused |
| GND | 5 | 6 | GND |
| Unused | 7 | 8 | Unused |
| Unused | 9 | 10 | Unused |

When power is supplied to J3, JP4 allows for one of two different DC voltage sources to be applied to the DAC installed on the EVM. Review the schematic and PCB silkscreen for details.

4.1 DAC Power

JP4 allows the user to select the power supply used by the DAC installed in position U1 on the EVM. When JP4 is in the default factory position (Shunt on pins 1-2), power to the DAC comes from J3 pin 5, which is designated as a +5VDC input. When the shunt on JP4 is moved to pins 2-3, the user may apply an external power source to the DAC via TP1, referenced to TP4.

4.2 Stand-Alone Operation

When used as a stand-alone EVM, the analog power can be applied directly to TP5 referenced to pin TP4. Optimal performance of the EVM requires a clean, well-regulated power source.

CAUTION

The DACs that are compatible with this EVM have a variety of power supply requirements. Check the appropriate data sheets and verify that all power supplies are within the safe operating limits of the converter before applying power to the EVM.

5 EVM Operation

5.1 Analog Output

The analog output from the EVM is applied directly to J2 (top or bottom side) pins 2-16 (even). The DACxx68EVM does not provide any additional filtering or buffering of the output voltage, so that the user may evaluate the converter's low-glitch output performance.

5.2 Reference In/Out

The DAC8568, DAC8168, and DAC7568 provide the ability to use an internal reference or an external reference in the range of 0 V to 2.5 V. The DACxx58 internal reference is powered OFF by default. The following sections describe how to apply an external reference or use the internal reference.

5.2.1 External Reference

provides an external reference via JP3 (shorted pins 1-2 by default) from U2, a precision REF5025 source of 2.5 VDC. When JP3 is shorted on pins 2-3, an external reference may be applied to J2 pin 20 or TP3 reference to TP2.

These external reference sources are applied to pin 8 of the DAC installed on the EVM and are also fed to U3, a unity gain buffer configured OPA379. The output of U3 may be used to provide a 2.5-V, common-mode input to external signal-conditioning circuits via J2 pin 15.

5.2.2 Internal Reference

The internal reference can be powered up and powered down by using a serial command that requires a 32-bit write sequence as defined in the device data sheet (see the *Serial Interface section and Table 1* of document [SBAS430](#)).

CAUTION

Before enabling the internal reference of the DAC installed on the evaluation board, ensure that any shunt jumper applied to JP3 is completely removed.

The internal reference is enabled by setting the feature bits of the DAC control register. The DAC7568/8168/8568 data sheet provides specific details on both the static and flexible operating modes of the internal reference. For more information on using the internal reference source, review the *Internal Reference section* of document [SBAS430](#).

The internal reference source is applied to U3, a unity gain buffer configured OPA379. The output of U3 may be used to provide a 2.5-V, common-mode input to external signal conditioning circuits via J2 pin 15.

5.3 Digital Control

The digital control signals can be applied directly to J1 (top or bottom side). The DACxx68EVM also can be connected directly to a DSP or microcontroller capable of supplying the necessary serial control inputs. Visit the product folder for the EVM or the installed device for a current list of compatible interface and/or accessory boards.

5.4 SYNC

For synchronous DAC update operations, jumper JP5 is provided to allow the source selection of the signal applied to the SYNC input of the DAC installed on the EVM. The factory default condition for the EVM is to place a shunt jumper between pins 1-2 of JP5. This allows the Frame Sync (FS) signal from DSP host systems to be used as the SYNC input to the DAC. This signal originates from J1.7. When the shunt on JP5 is moved to pins 2-3, a GPIO input applied via J1.1 can be used to control the SYNC input to the DAC. JP2 may also be used to hold the LDAC input to the DAC low, allowing synchronous DAC output updates.

5.5 LOAD DAC (LDAC)

For asynchronous updates to the DAC outputs, jumper JP6 is provided to allow the source selection of the signal applied to the LDAC input of the DAC installed on the EVM. The factory default condition for the EVM is to place a shunt jumper between pins 1-2 of JP6. This allows the Timer Output (TOUT) signal from DSP host systems to be used as the LDAC input to the DAC. This signal originates from J1.17.

When the shunt on JP6 is moved to pins 2-3, a user-provided GPIO input may be applied to the LDAC pin via J1.15. This external input acts as an interrupt input to a DSP host processor which can in turn trigger a serial transfer to the DAC. JP2 can be used to hold the LDAC input to the DAC at ground potential if synchronous updates are required.

5.6 CLEAR (CLR)

Jumper JP1 is provided to allow the manual application of a CLR input pulse. The DACxx68EVM user may also apply a CLR input via J1 pin 19. Bringing the CLR pin low clears the content of all DAC registers and all DAC buffers, and replaces the code with the code determined by the clear code register. Jumper JP1 is open by default and uses a 10-kΩ pullup resistor (R1) to maintain logic high on the CLR input pin.

5.7 Default Jumper Locations

Table 3 provides a list of jumpers found on the EVM and their factory default conditions.

Table 3. EVM Default Jumper Settings

| Jumper | Shunt Position | Jumper Description |
|--------|----------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| JP1 | N/A | Allows CLR to be monitored or controlled via external pulse source. Used with signals applied to J1.19 |
| JP2 | OPEN | Allows LDAC to be kept at GND potential when installed; it is recommended to remove any shunt jumper installed on JP6 if JP1 is installed. |
| JP3 | Pins 1-2 | Controls reference voltage applied to the installed DAC. When JP3 is moved to pins 2-3, and external reference may be applied to the EVM via J2.20 or to TP3 referenced to TP2 |
| JP4 | Pins 1-2 | Analog power source control. Default is from J3.3. When shunt is placed on pins 2-3, power to the DAC may be applied to TP1 referenced to TP4. |
| JP5 | Pins 1-2 | Controls SYNC source selection – see Section 5.3 for details |
| JP6 | Pins 1-2 | Controls LDAC source selection – see Section 5.4 for details |

The following diagram provides an overview of the DACxx68 assembly and locations of the various jumpers and connectors.

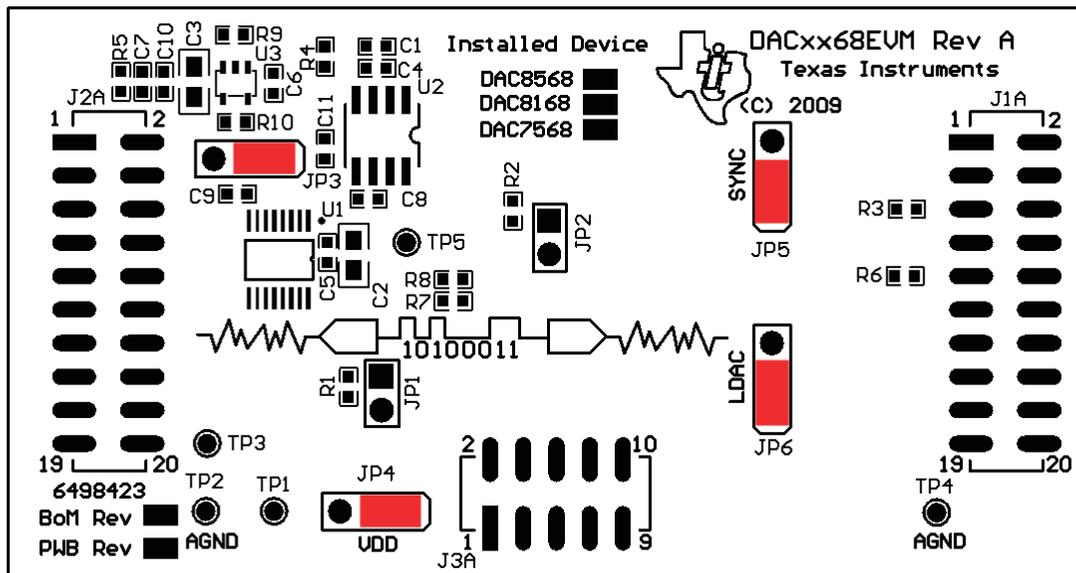


Figure 1. Top Layer Assembly Drawing and Jumper Locations

6 Bill of Material and EVM Schematic

Table 4 contains a complete bill of materials for the DACxx68EVM. The schematic diagram also is provided for reference.

6.1 Bill of Materials

Table 4. Bill of Materials

| Designators | Description | Manufacturer | Mfg. Part Number |
|------------------------|----------------------------------------|--------------|-----------------------|
| C1, C11 | CAP CER 10UF 6.3V X5R 20% 0603 | TDK | C1608X5R0J106M |
| C2 | CAP CER 10UF 16V X5R 0805 | Taiyo Yuden | EMK212BJ106KG-T |
| C3 | CAP CER 22UF 10V X5R 0805 | Taiyo Yuden | LMK212BJ226MG-T |
| C4, C5, C6 | CAP CER .10UF 50V X7R 10% 0603 | TDK | C1608X7R1H104K |
| C7, C10 | NI | | |
| C8 | CAP CER 1.0UF 16V X7R 10% 0603 | TDK | C1608X7R1C105K |
| C9 | CAP CER 2.2UF 10V X5R 0603 | TDK | C1608X5R1A225K |
| J1A, J2A (Top Side) | 10 Pin, Dual Row, SM Header (20 Pos.) | Samtec | TSM-110-01-T-DV-P |
| J1B, J2B (Bottom Side) | 10 Pin, Dual Row, SM Header (20 Pos.) | Samtec | SSW-110-22-F-D-VS-K |
| J3A (Top Side) | 5 Pin, Dual Row, SM Header (10 Pos.) | Samtec | TSM-105-01-T-DV-P |
| J3B (Bottom Side) | 5 Pin, Dual Row, SM Header (10 Pos.) | Samtec | SSW-105-22-F-D-VS-K |
| JP1, JP2 | Header Strip (2 x 1) | Samtec | TSW-102-07-L-S |
| JP3 - JP6 | Header Strip (3 x 1) | Samtec | TSW-103-07-L-S |
| R1, R2, R10 | RES 10.0K OHM 1/10W 1% 0603 SMD | Yageo | RC0603FR-0710KL |
| R3, R6 | RES 0 OHM, 1/16W 5% 0603 Chip Resistor | Yageo | RC0603JR-070RL |
| R4 | RES 1.5 OHM 1/10W 5% 0603 SMD | Yageo | RC0603JR-071R5L |
| R5 | RES 2.00K OHM 1/10W 1% 0603 SMD | Yageo | RC0603FR-072KL |
| R7, R8, R9 | RES 33.0 OHM 1/10W 1% 0603 SMD | Yageo | RC0603FR-0733RL |
| TP1, TP3, TP5 | TEST POINT PC MINI 0.040"D RED | Keystone | 5000 |
| TP2, TP4 | TEST POINT PC MINI 0.040"D BLACK | Keystone | 5001 |
| U1 ⁽¹⁾ | Device Under Test | TI | DAC8568/8168/7568ICPW |
| U2 | IC PREC V-REF 2.5V LN 8-SOIC | TI | REF5025AID |
| U3 | IC OPAMP GP R-R 90KHZ SOT23-5 | TI | OPA379AIDBVT |

⁽¹⁾ The device installed at location U1 is dependent on the EVM ordered. This device is soldered to the board for best performance. U1 may be replaced with any device listed in the EVM Compatible Device Data Sheets table found at the beginning of this document.

7 Related Documentation from Texas Instruments

The following devices data sheet is DACxx68EVM compatible.

- *DAC7568, DAC8168, DAC8568, 12-/14-/16-Bit, Octal-Channel, Ultra-Low Glitch, Voltage Output Digital-to-Analog Converters With 2.5V, 2ppm/°C Internal Reference* data sheet ([SBAS430](#))

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EVM Warnings and Restrictions

It is important to operate this EVM within the input voltage range of 0 V to 5 V and the output voltage range of 0 V to 5 V .

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 30° C. The EVM is designed to operate properly with certain components above 30° C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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